

BONDING APPARATUS AND BONDING METHOD

ABSTRACT

The bonding apparatus comprises: supporting means (4, 15) for supporting a substrate (1), on which semiconductor devices (3) are adhered by a non-conductive adhesive (2); and heating/pressing means (8, 24, 10, 25) for heating and pressing the substrate (1), the heating/pressing means (8, 24, 6, 17) having a heat source (13) and a clamping face (10a, 28b). The substrate (1) is moved toward the clamping face (10a, 28b) of the heating/pressing means (8, 24, 6, 17) so as to preheat the substrate (1) and the semiconductor devices (3). Then, the semiconductor devices (3) are pressed onto the clamping face (10a, 28b) of the heating/pressing means (8, 24, 10, 25) so as to cure the non-conductive adhesive (2) and bond bumps (3a) of the semiconductor devices (3) to terminal sections (1a) of the substrate (1).

FIGURE 1A